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- (71) Applicant (for all designated States except US): **DOW GLOBAL TECHNOLOGIES LLC** [US/US]; 2040 Dow Center, Midland, Michigan 48674 (US).
- (72) Inventors; and
- (75) Inventors/Applicants (for US only): **XIONG, Jiawen** [CN/CN]; 3339 Lane, Shangnan Road, Shanghai (CN). **CHEN, Hongyu** [CN/CN]; Room 102, No.57, Lane 50, Guanglan Road, Zhangjiang, Shanghai 201203 (CN). **MULLINS, Michael J.** [US/US]; 1 Hermann Museum, Houston, 77004 (US). **ZHANG, Chao** [CN/CN]; Room 104,15F Lab Building, 130 Meilong Road, Shanghai (CN). **LIAO, Annie Guihong** [CN/CN]; 42 Mailbox, #2 Beiyitia, Zhongguancun, Beijing (CN). **ZHANG, Wayne Yi** [CN/CN]; 1A, No. 32, Lane 999, Changshou Road, Shanghai 200041 (CN).

- (74) Agent: **LIU, SHEN & ASSOCIATES**; A0601, Huibin Building, No.8 Beichen Dong Street, Chaoyang District, Beijing 100101 (CN).

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(54) Title: CURABLE COMPOSITIONS

(57) Abstract: Embodiments include curable compositions including an epoxy resin and a hardener component including a terpolymer having first constitutional unit, a second constitutional unit, and a third constitutional unit, where the epoxy group to the second constitutional unit has a molar ratio in a range of 1.0:1.0 to 2.7:1.0. Embodiments include prepreps that include a reinforcement component and the curable composition and an electrical laminate formed with the curable composition.

